

WORKSHOP SCIENTIFIC PROGRAM

Monday, October 2, 2006

Session 0: Opening Session 09:50-10:00

- 09:50-10:00 **Introductory**
Junichi Murota,
Laboratory for Nanoelectronics and Spintronics, Research Institute of Electrical
Communication, Tohoku Univ., Japan

Session 1: Invited Session (1) 10:00-12:00 (4F Conference Room)

- 10:00-10:30 I-01: **“SiGe:C BiCMOS Technologies for High Frequency Applications”**,
Bernd Tillack, Bernd Heinemann, Dieter Knoll, Holger Rucker, Gerhard Fischer,
Wolfgang Winkler, Wolfgang Mehr,
IHP, Germany
- 10:30-11:00 I-02: **“MMICs using SiGe BiCMOS”**,
Katsuyoshi Washio, Nobuhiro Shiramizu, Toru Masuda,
Central Research Laboratory, Hitachi, Ltd., Japan
- 11:00-11:30 I-03: **“Mobility-Enhanced Device Technologies Using SiGe/Ge MOS Channels”**,
Shinichi Takagi^{1,2}, T. Tezuka³, T. Irisawa³, S. Nakaharai³, N. Hirashita³, Y. Moriyama³, K.
Usuda³, K. Ikeda³, N. Taoka³, Y. Yamashita³, M. Harada³, T. Maeda¹, T. Yamamoto³ and
N. Sugiyama³,
¹MIRAI-AIST, ²Univ. Tokyo, ³MIRAI-ASET, Japan
- 11:30-12:00 I-04: **“Strained Heterostructure p-MOSFETs”**,
Cait Ní Chléirigh, I. Åberg, G. Xia, J. L. Hoyt,
Microsystems Technology Laboratories, Department of Electrical Engineering and
Computer Science, MIT, USA

12:00-13:20 **Lunch**

Session 2: Short Presentation (1) 13:20-14:20 (4F Conference Room)

- 13:20-13:24 P-01: **“Strain and Conductivity Behavior of Stripe Patterned Si/Si_{1-x}Ge_x/Si(100) Heterostructures”**
J. Uhm, M. Sakuraba, J. Murota,
Laboratory for Nanoelectronics and Spintronics, Research Institute of Electrical
Communication, Tohoku Univ., Japan
- 13:24-13:28 P-02: **“Fabrication of Sub-100-nm Gate-Length SiGe-Heterochannel MOSFETs with In-Situ Doped Selectively Epitaxial SiGe Source/Drain”**,
S. Takehiro¹, M. Sakuraba¹, T. Tsuchiya², J. Murota¹,
¹Laboratory for Nanoelectronics and Spintronics, Research Institute of Electrical
Communication, Tohoku Univ., ²Interdisciplinary Faculty of Science and Engineering,
Shimane Univ., Japan
- 13:28-13:32 P-03: **“Mobility and 1/f Noise Dependence on In-plane Channel Direction of SiGe Channel PMOSFETs”**,
Masato Toita, Tomohiko Chiaki,
Asahi Kasei Microsystems, Japan
- 13:32-13:36 P-04: **“Low Temperature Formation of SiGe/Glass Structures for System-in-Display Application”**,
M. Miyao, H. Kanno, T. Sadoh,
Department of Electronics, Kyushu Univ., Japan

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- 13:36-13:40 P-05: **“Formation of High Quality SiGe Virtual Substrate for Strained SOI Application”**,
M. Tanaka, T. Sadoh, M. Miyao,
Department of Electronics, Kyushu Univ., Japan
- 13:40-13:44 P-06: **“Gas-source MBE of 3C-SiC(111) on Si(110) substrate using organosilane”**,
A. Konno¹, M. Suemitsu¹, Y. Narita², T. Ito¹, K. Yasui³, H. Nakazawa⁴, T. Endoh⁵,
¹Center for Interdisciplinary Research, Tohoku Univ., ²Kyushu Institute of Technology,
³Dept. Electrical Engineering, Nagaoka Univ. Technology, ⁴Department of Materials
Science and Technology, Hirosaki Univ., ⁵Research Institute of Electrical and
Communication, Tohoku Univ., Japan
- 13:44-13:48 P-07: **“Scanning-tunneling-microscope observation on initial oxidization at Si surfaces”**,
Y. Takahashi¹, H. Togashi¹, A. Kato¹, H. Asaoka², A. Konno¹, M. Suemitsu¹, Y. Teraoka²,
A. Yoshigoe²,
¹Center for Interdisciplinary Research, Tohoku Univ., ²Japan Atomic Energy Agency,
Tokai, Japan
- 13:48-13:52 P-08: **“Oxygen uptake during ultraviolet-ozone oxidation of HF-treated Si(110) surfaces”**,
S. Hasegawa¹, T. Nakano¹, K. Ohmura², H. Matsuzawa², S. Asami³, M. Suemitsu¹,
¹Center for Interdisciplinary Research, Tohoku Univ., ²NEC-TOKIN, ³Sendai National
College of Technology, Japan
- 13:52-13:56 P-09: **“Low-Temperature Growth of Highly Crystallized Poly-Si Thin Films on polyethylene-terephthalate (PET)”**,
M. Matsumoto¹, M. Suemitsu¹, T. Yara², S. Nakajima², T. Uehara², Y. Toyoshima³, S.
Itou⁴,
¹Center for Interdisciplinary Research, Tohoku Univ., ²Sekisui Chemicals Co. Ltd.,
³Energy Technology Research Institute, AIST, ⁴Institute for Materials Research, Tohoku
Univ., Japan
- 13:56-14:00 P-10: **“Strain Relaxation of Strained-Si Layers on (001) Si_{1-x}Ge_x-on-Insulator Substrates due to Misfit Dislocations”**,
N. Hirashita¹, Y. Moriyama¹, E. Toyoda², N. Sugiyama¹, S. Takagi³,
¹MIRAI-ASET, ²Toshiba Ceramics Co., Ltd., ³MIRAI-AIST, Japan
- 14:00-14:04 P-11: **“Reduction of dislocation density in SGOI structures by two step oxidation and condensation method”**,
N. Sugiyama¹, S. Nakaharai¹, N. Hirashita¹, T. Tezuka¹, Y. Moriyama¹, K. Usuda¹, S.
Takagi^{2,3},
¹MIRAI-ASET, ²MIRAI-AIST, ³Univ. Tokyo, Japan
- 14:04-14:08 P-12: **“Oxidation and Reduction of GeO_x/Ge and GeO_x/Si in O₂ and N₂ Annealing”**,
H. Nomura, T. Takahashi, T. Nishimura, K. Kita, A. Toriumi,
Department of Materials Engineering, Univ. Tokyo, Japan
- 14:08-14:12 P-13: **“Ge MIS Characteristics with GeN_x and GeON Layers Nitrided by Atomic Nitrogen Irradiation”**,
T. Takahashi, H. Nomura, T. Nishimura, K. Kita, A. Toriumi,
Department of Materials Engineering, Univ. Tokyo, Japan
- 14:12-14:16 P-14: **“Subtleties in the epitaxial growth of Ge/Si nanstructures revealed by Raman scattering in combination with stable isotopes tracing”**,
O. Moutanabbir, S. Miyamoto, K. M. Itoh,
Department of Applied Physics and Physico-Informatics, Keio Univ., Japan
- 14:16-14:20 P-15: **“Current Voltage Characterization in MIM Capacitor with High-K Dielectric by the Nonlinear RC Decay Method”**,
Jung-Hsiang Lee,
Department of Electronic Engineering, Ching Yun Univ., Taiwan. R.O.C.
- 14:20-14:50 **Break**

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Session 3: Invited Session (2) 14:50-16:20 (4F Conference Room)

- 14:50-15:20 I-05: **“Ge MOSFETs and high k gate dielectrics: a happy marriage thanks to thin epitaxial Si layers”**,
Matty Caymax¹, F. Leys¹, A. Dimoulas², S. Van Elshocht¹, M. Houssa³, A. Delabie¹, T. Conard¹, B. De Jaeger¹, B. Kaczer¹, R. Bonzom¹, D. Nelis¹, W. Vandervorst¹, R. Loo¹, M. Meuris¹, M. M. Heyns¹,
¹IMEC, Belgium, ²MBE Laboratory, Institute of Materials Science, NCSR DEMOKRITOS, ³Deptm. Electrical Engineering, K.U. Leuven, Belgium
- 15:20-15:50 I-06: **“Interface Properties of Ge with High-k Dielectrics and Metals”**,
Akira Toriumi, Koji Kita, Tomonori Nishimura,
Department of Materials Engineering, Univ. Tokyo, Japan
- 15:50-16:20 I-07: **“Growth and application of Ge dots in DotFETs”**,
Olaf Kirfel, M. Oehme, K. Lyutovich, E. Kasper,
Institut für Halbleitertechnik, Univ. Stuttgart, Germany
- 16:20-16:30 **Break**

Session 4: Invited Session (3) 16:30-18:00 (4F Conference Room)

- 16:30-17:00 I-08: **“Si Photonics -On chip optical interconnection and beyond-”**,
Kazumi Wada,
Department of Materials Engineering, Univ. Tokyo, Japan
- 17:00-17:30 I-09: **“Si(Ge)- based structures and materials for spintronic applications: from MRAM to ferromagnetic semiconductors”**,
Vinh Le Thanh, S. Olive-Mendez, L. Michez, J. Derrien,
CRMCN-CNRS, Univ. Méditerranée, Campus Luminy, France
- 17:30-18:00 I-10: **“Control of Electronic Charged States of Si-based Quantum Dots for Floating Gate Application”**,
Seiichi Miyazaki, K. Makihara, M. Ikeda,
Graduate School of Advanced Sciences of Matter, Hiroshima Univ., Japan

Banquet : 19:00-21:00 (Hotel Bel Air 1F)

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Session 5: Short Presentation (2) 08:45-09:41 (4F Conference Room)

- 08:45-08:49 P-16: “**B Atomic Layer Formation on Si_{1-x}Ge_x(100) by Ultraclean LPCVD System**”
K. Ishibashi, M. Sakuraba, J. Murota, Y. Inokuchi, Y. Kunii, H. Kurokawa,
Laboratory for Nanoelectronics and Spintronics, Research Institute of Electrical
Communication, Tohoku Univ., Japan
- 08:49-08:53 P-17: “**Highly Strained-Si/Relaxed-Ge Epitaxial Growth on Si(100) by ECR Plasma
CVD and Evaluation of Thermal Stability**”,
K. Sugawara, M. Sakuraba, J. Murota,
Laboratory for Nanoelectronics and Spintronics, Research Institute of Electrical
Communication, Tohoku Univ., Japan
- 08:53-08:57 P-18: “**Super-Critically-Thick Strained Si/SiGe CMOS Technology with
Selective-Epitaxial-Si Shallow-Trench Isolation**”,
M. Miyamoto¹, N. Sugii², Y. Yoshida¹, Y. Hoshino³, Y. Kimura², M. Kondo³, K. Ohnishi³,
¹Micro Device Division, Hitachi, Ltd., ²Central Research Laboratory, Hitachi, Ltd.,
³Renesas Technology Corp., Japan
- 08:57-09:01 P-19: “**A robust design approach for optimization of SiGe selective epitaxial growth
technique**”,
S. Eguchi¹, I. Miyashita¹, S. Nagashima², R. Takada¹, Y. Kagotoshi¹, H. Toyoda², A.
Kanai¹, N. Machida¹,
¹Renesas Technology Corp., ²Renesas Eastern Japan Semiconductors Inc., Japan
- 09:01-09:05 P-20: “**Band Engineering and Process Technologies in SiGe BiCMOS for
Highly-Sensitive and High-Speed Communication LSIs**”,
Makoto Miura¹, Hiromi Shimamoto³, Reiko Hayami¹, Akihiro Kodama³, Tatsuya
Tominari², Takashi Hashimoto², Katsuyoshi Washio¹,
¹Central Research Laboratory, Hitachi, Ltd., ²Micro Device Division, Hitachi Ltd.,
³Renesas Northern Japan Semiconductor. Inc., Japan
- 09:05-09:09 P-21: “**Formation of Highly-Crystallized Ge:H Films from VHF Inductively-Coupled
Plasma of GeH₄**”,
T. Sakata, K. Makihara, S. Higashi, S. Miyazaki,
Graduate School of Advanced Sciences of Matter, Hiroshima Univ., Japan
- 09:09-09:13 P-22: “**Characterization of Chemical Bonding Features of Silicon Oxynitride Films
Formed on Ge(100) Surface**”,
H. Nakagawa, A. Ohta, H. Murakami, S. Higashi, S. Miyazaki,
Graduate School of Advanced Sciences of Matter, Hiroshima Univ., Japan
- 09:13-09:17 P-23: “**Semiconductor Diode Laser Annealing of Amorphous Ge Films**”,
K. Sakaike, S. Higashi, H. Kaku, T. Sakata, H. Murakami, S. Miyazaki,
Graduate School of Advanced Sciences of Matter, Hiroshima Univ., Japan
- 09:17-09:21 P-24: “**The hole density dependence of hole mobility in compressively strained Ge
channel modulation-doped structures**”,
K. Sawano¹, Y. Kunishi¹, H. Satoh¹, K. Nakagawa², Y. Shiraki¹,
¹Research Center for Silicon Nano-Science, Advanced Research Laboratories, Musashi
Inst. Technology, ²Center for Crystal Science and Technology, Musashi Inst. Technology,
Japan

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- 09:21-09:25 P-25: “**Dislocation Structure and Strain Relaxation of SiGe and Ge Sub-micron Stripe Lines on Si(001) Substrates**”,
O. Nakatsuka¹, S. Mochizuki², A. Sakai², H. Kondo², K. Yukawa², M. Ogawa³, and S. Zaima²,
¹EcoTopia Science Institute, Nagoya Univ., ²Department of Crystalline Materials Science, Graduate School of Engineering, Nagoya Univ., ³Center for Cooperative Research in Advanced Science and Technology, Nagoya Univ., Japan
- 09:25-09:29 P-26: “**Mosaicity and Dislocations in Strain-Relaxed SiGe Buffer Layers on SOI Substrates**”,
O. Nakatsuka¹, N. Taoka², A. Sakai², S. Mochizuki², M. Ogawa³, S. Zaima²,
¹EcoTopia Science Institute, Nagoya Univ., ²Department of Crystalline Materials Science, Graduate School of Engineering, Nagoya Univ., ³Center for Cooperative Research in Advanced Science and Technology, Nagoya Univ., Japan
- 09:29-09:33 P-27: “**P atomic Layer Doping at Heterointerface of Epitaxial Si Layer and Si_{1-x}Ge_x(100) Substrate by Alternate Surface Reaction of PH₃ and Si₂H₆ in Ultraclean LPCVD**”,
Y. Chiba, M. Sakuraba, J. Murota,
Laboratory for Nanoelectronics and Spintronics, Research Institute of Electrical Communication, Tohoku Univ., Japan
- 09:33-09:37 P-28: “**Thermal Stability of Nitrided Si Atomic Layer on Ge(100) Using Low Pressure CVD**”,
N. Akiyama, M. Sakuraba, J. Murota,
Laboratory for Nanoelectronics and Spintronics, Research Institute of Electrical Communication, Tohoku Univ., Japan
- 09:37-09:41 P-29: “**Electrical Characteristics of Hole Resonant Tunneling Diodes with High Ge Fraction Si/Strained Si_{1-x}Ge_x Heterostructures on Si(100) Grown by Low-Temperature Ultraclean LPCVD**”,
T. Seo, M. Sakuraba, J. Murota,
Laboratory for Nanoelectronics and Spintronics, Research Institute of Electrical Communication, Tohoku Univ., Japan
- 09:41-10:00 **Break**

Session 6: Invited Session (3) 10:00-11:00 (4F Conference Room)

- 10:00-10:30 I-11: “**Formation of high quality SiGe buffers on Si and transport properties of structures grown on them**”,
Yasuhiro Shiraki,
Advanced Research Laboratories, Musashi Inst. Technology, Japan
- 10:30-11:00 I-12: “**Buffer layer technology with misfit dislocation engineering**”,
Akira Sakai¹, Osamu Nakatsuka², Masaki Ogawa³, Shigeaki Zaima¹,
¹Graduate School of Engineering, Nagoya Univ., ²EcoTopia Science Institute, Nagoya Univ., ³Center for Cooperative Research in Advanced Science and Technology, Nagoya Univ., Japan

Session 7: Poster Presentation (P-01 ~ P-29) 11:00-12:20 (5F Hallway)

(Boards for posters are available during Workshop.)

12:20-13:20 **Lunch**

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Session 8: Regular Session (1) 13:20-15:10 (4F Conference Room)

- 13:20-13:30 “**Session Introductory**”,
J. Murota,
Laboratory for Nanoelectronics and Spintronics, Research Institute of Electrical
Communication, Tohoku Univ., Japan
- 13:30-13:50 O-01: “**Hot-Carrier-Degradation of Hetero-Interface in SiGe/Si-Hetero-MOSFETs**”
T. Tsuchiya¹, M. Sakuraba², J. Murota²,
¹Interdisciplinary Faculty of Science and Engineering, Shimane Univ., ²Research
Institute of Electrical Communication, Tohoku Univ., Japan
- 13:50-14:10 O-02: “**Design of intrinsic and extrinsic base process of SiGeC HBT**”,
Yukihiro Kiyota¹, Hideo Yamagata²
¹SONY Corp., ²SONY Semiconductor Kyusyu., Japan
- 14:10-14:30 O-03: “**Low-Temperature Formation of Fe₃Si/SiGe Structures for Spintronics
Application**”,
T. Sadoh, K. Ueda, M. Kumano, M. Miyao,
Department of Electronics, Kyushu Univ., Japan
- 14:30-14:50 O-04: “**SiGe Sputter Epitaxy and Its Application to Quantum Effect Devices**”,
Y. Suda, H. Hanabusa, T. Kobayashi, Y. Takahashi, H. Maekawa
Graduate School of Engineering, Tokyo Univ. Agriculture & Technology, Japan
- 14:50-15:10 O-05: “**Control of strain and dislocation structures in Ge_{1-x}Sn_x buffer layers on
virtual Ge substrates**”,
S. Takeuchi¹, A. Sakai¹, O. Nakatsuka², M. Ogawa³, S. Zaima¹,
¹Graduate School of Engineering, Nagoya Univ., ²EcoTopia Science Institute, Nagoya
Univ., ³Center for Cooperative Research in Advanced Science and Technology, Nagoya
Univ., Japan
- 15:10-15:30 **Break**

Session 9: Regular Session (2) 15:10-17:20 (4F Conference Room)

- 15:30-15:50 O-06: “**Growth of high quality Ge epitaxial layer on Si(100) substrate using ultra thin
Si_{0.5}Ge_{0.5} buffer**”,
J. Nakatsuru, H. Date, S. Mashiro, M. Ikemoto,
Canon ANELVA Corp., Japan
- 15:50-16:10 O-07: “**A Study on Low-Temperature Pre-Epi Surface Treatment Using Cl-based and
Si-based Gas Mixture**”,
J. Wang, K. Yamamoto, A. Moriya, Y. Hashiba, Y. Inokuchi, Y. Kunii,
Hitachi Kokusai Electric Inc., Japan
- 16:10-16:30 O-08: “**Initial oxidation of HF acid treated SiGe (100) surfaces**”,
F. Hirose, M. Nagato, Y. Kinoshita,
Faculty of Engineering, Yamagata Univ., Japan

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- 16:30-16:50 O-09: **“Epitaxial Growth of Group IV Semiconductor in ECR Plasma Enhanced CVD”**,
M. Sakuraba, D. Muto, M Mori, K. Sugawara, J. Murota,
Laboratory for Nanoelectronics and Spintronics, Research Institute of Electrical
Communication, Tohoku Univ., Japan
- 16:50-17:10 O-10: **“Low-temperature formation of ultrathin SiC films on Si substrates and its application to ubiquitous devices”**,
M. Suemitsu¹, A. Konno¹, Y. Narita², T. Ito¹, K. Yasui³, H. Nakazawa⁴, and T. Endoh⁵,
¹Center for Interdisciplinary Research, Tohoku Univ., ²Kyushu Institute of Technology,
³Department of Electrical Engineering, Nagaoka Univ. of Technology, ⁴Department of
Materials Science and Technology, Hirosaki Univ., ⁵Research Institute of Electrical and
Communication, Tohoku Univ., Japan
- 17:10-17:20 **Closing Remarks**